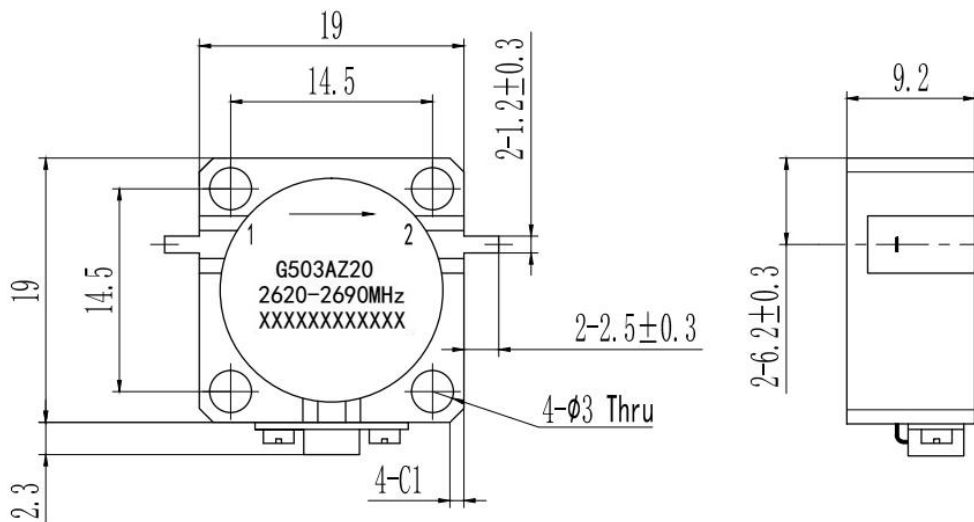


### 1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40 ~ 85°C
- Compact Package Design for PCB Applications

### 2.Dimensions



### 3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G503A[925-960]MHz	0.925	0.960	0.943	0.035	22	0.3	1.17	60	
G503A[1710-1785]MHz	1.710	1.785	1.7475	0.075	23	0.25	1.17	60	
G503A[1805-1880]MHz	1.805	1.880	1.8375	0.075	25	0.25	1.15	60	
G503A[1880-1920]MHz	1.880	1.920	1.9000	0.040	25	0.25	1.15	100	
G503A[1920-1980]MHz	1.920	1.980	1.9500	0.060	23	0.25	1.17	60	
G503A[1930-1990]MHz	1.930	1.990	1.9600	0.060	23	0.25	1.17	60	
G503A[2010-2025]MHz	2.010	2.025	2.0170	0.015	25	0.25	1.17	60	
G503A[2110-2170]MHz	2.110	2.170	2.1400	0.060	23	0.25	1.17	60	
G503A[2620-2690]MHz	2.620	2.690	2.6550	0.070	23	0.25	1.17	60	